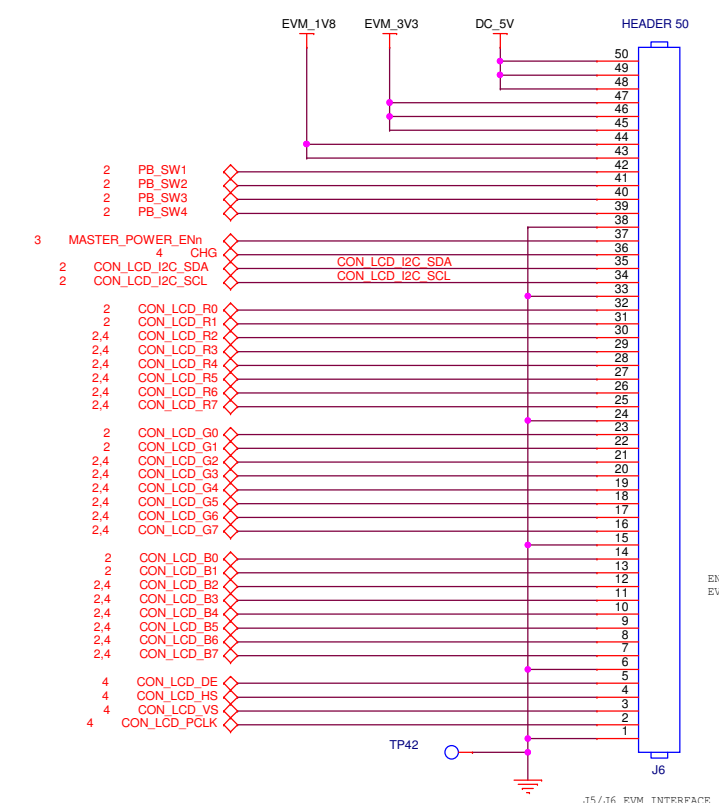
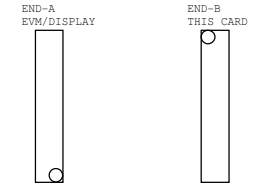


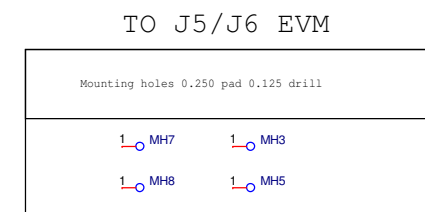
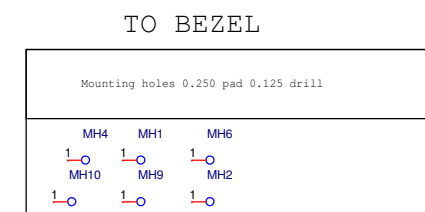
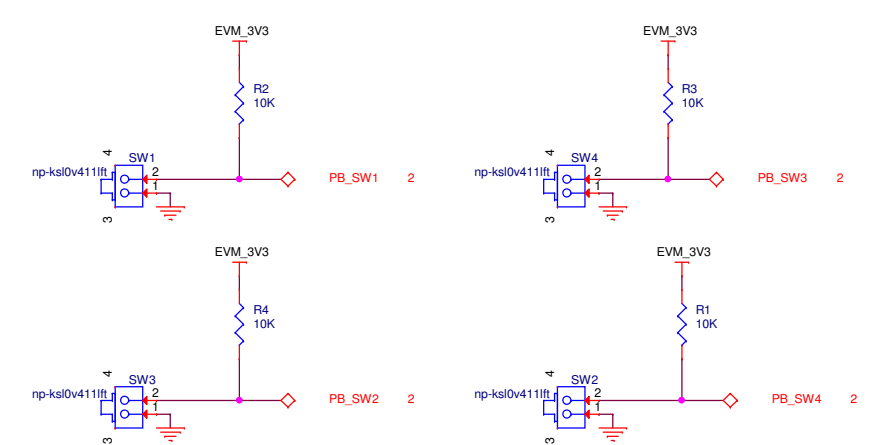
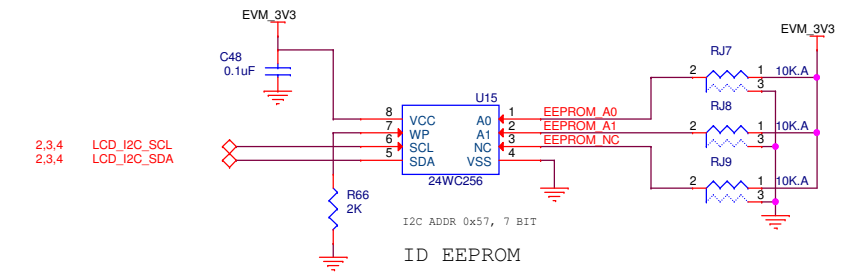
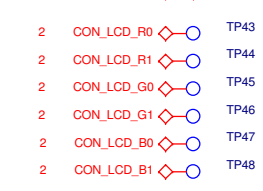
LOCATE AT THE EVM CONNECTOR,  
EVM HAS PULLUPS ON I2C.  
FXM USE FOR SIGNAL ISOLATION.



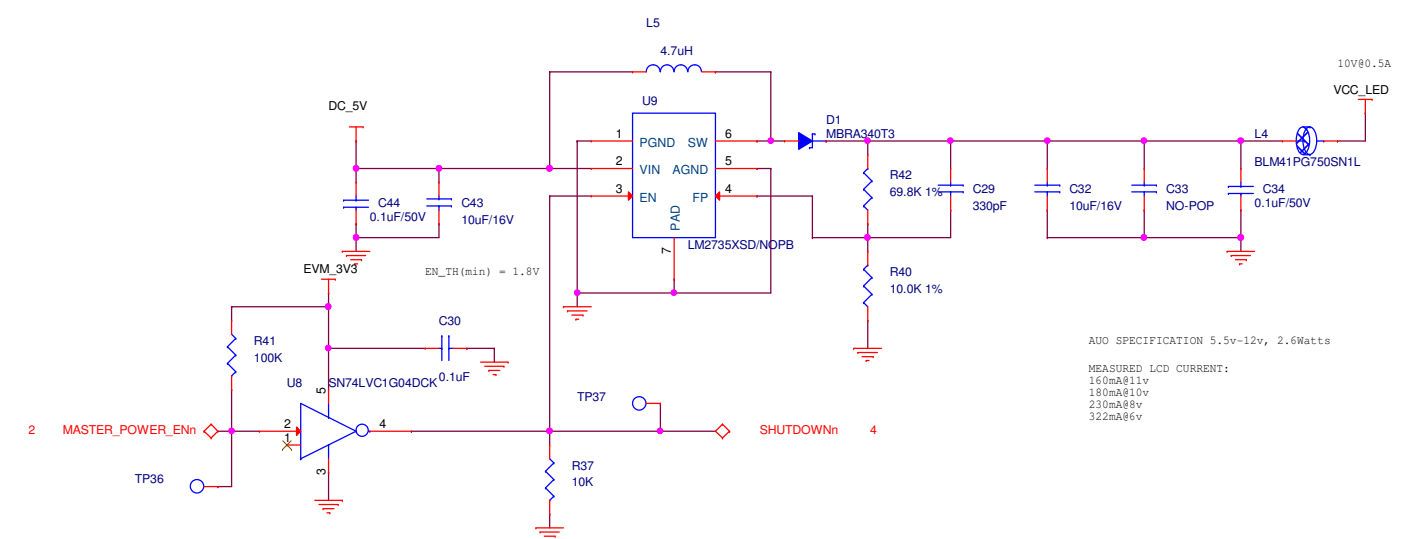
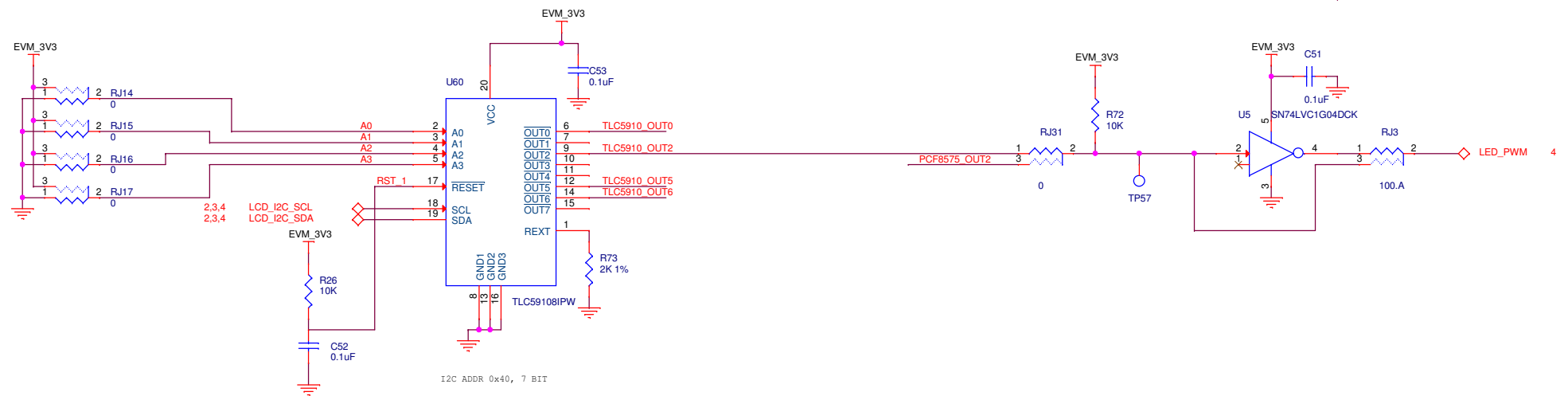
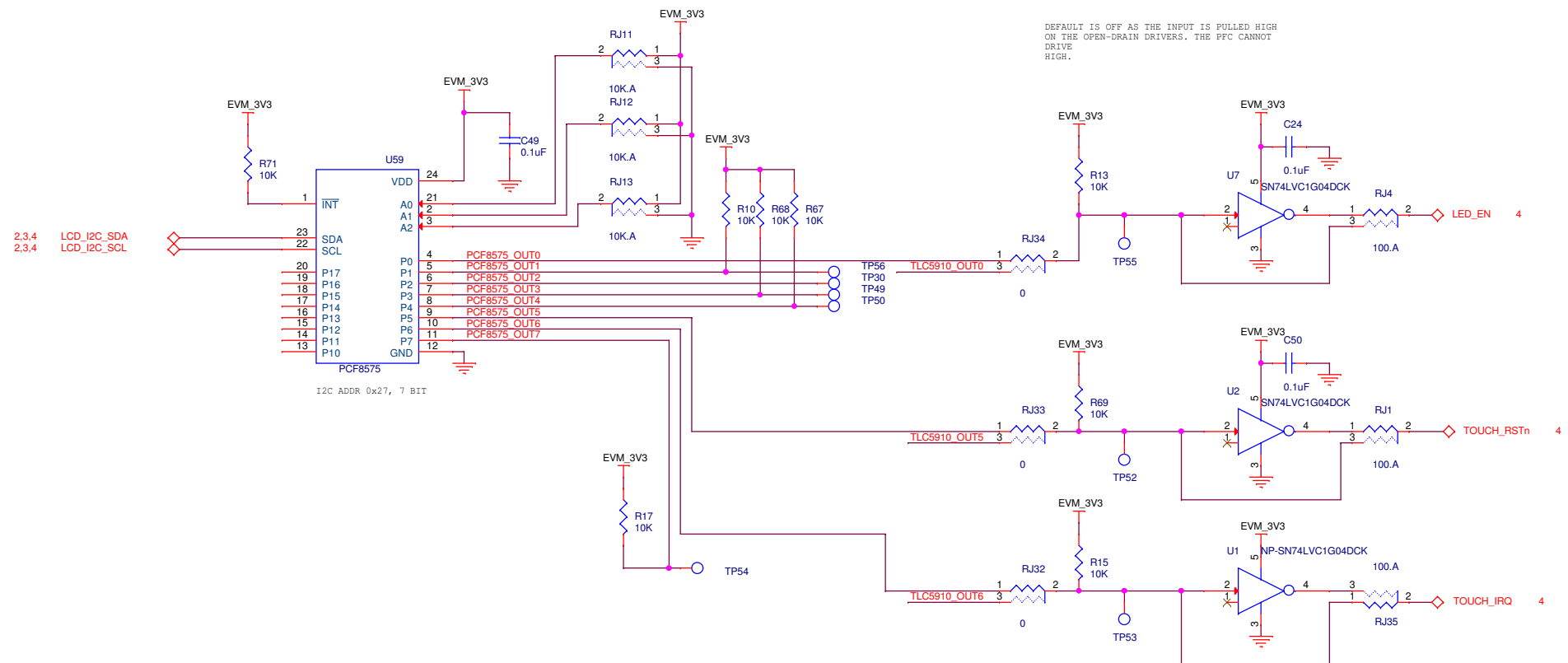
CONNECTORS J1, AND J4 ARE MIRRORED. WHEN THE SAME CONNECTOR IS USED ON BOTH END A AND END B THE PIN 1 DOES NOT ALIGN. SO WE MIRROR ON THIS SCHEMATIC SO THAT CONNECTOR PIN 1 MARKING MATCHES THE CONNECTOR. J3 IS NOT MIRRORED AS IT IS MIRRORED ON THE LCD PANEL.



FOR 24 BIT DISPLAY DIRECT MAP.  
FOR 18 BIT DISPLAY SHFT DOWN 2 BITS.



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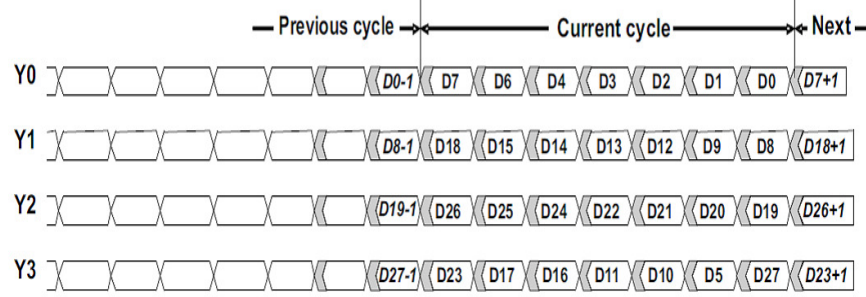
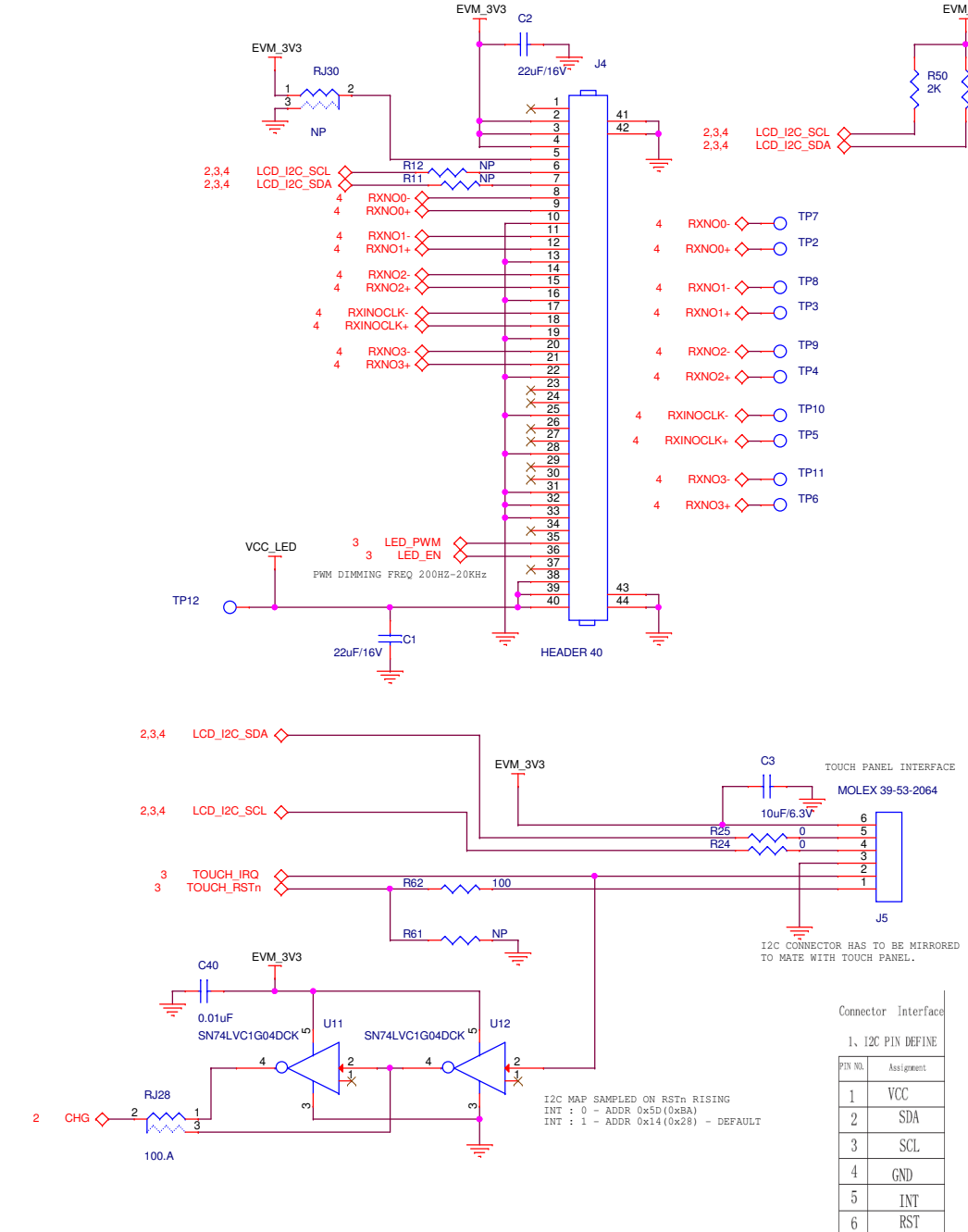
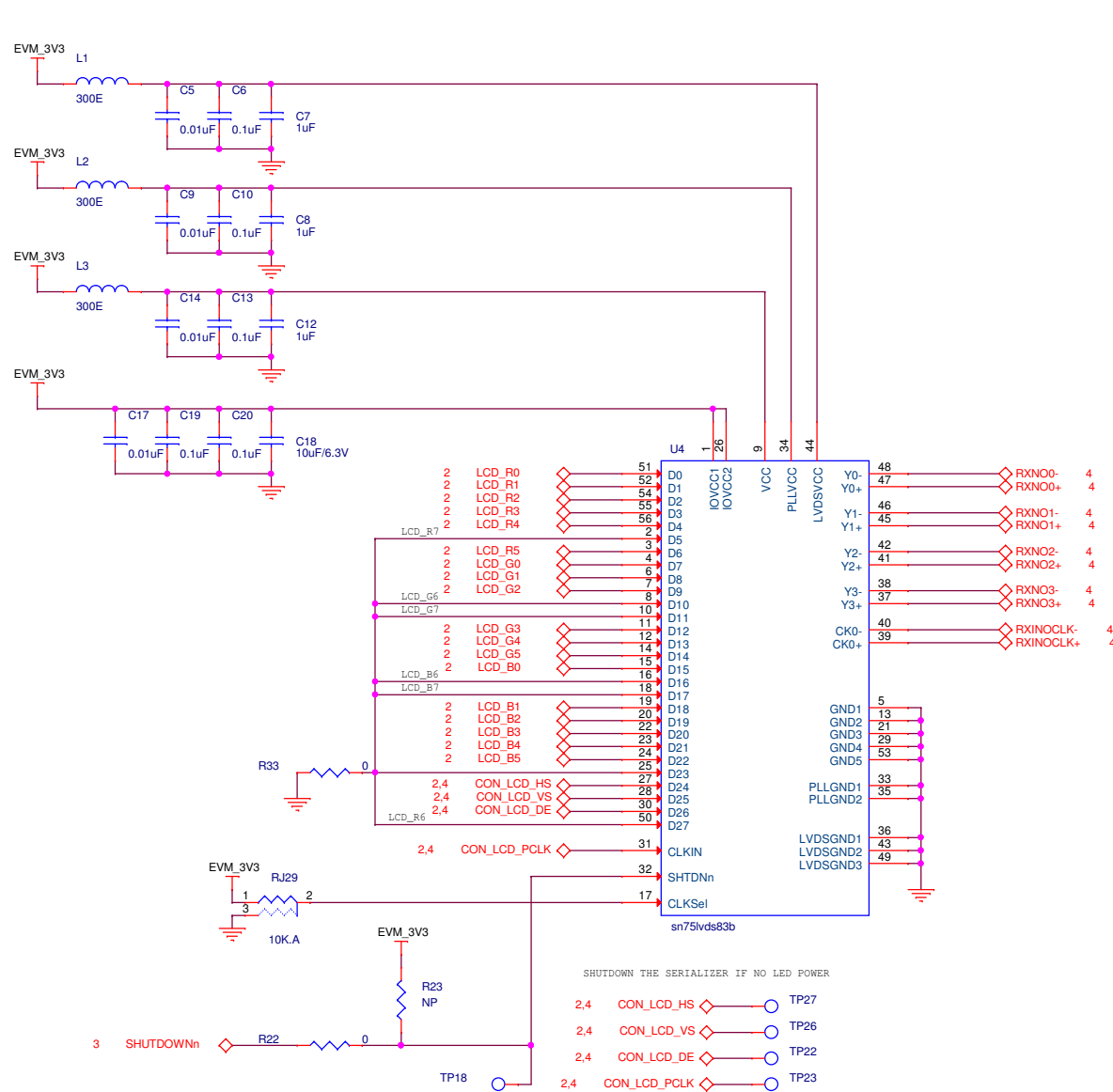


Figure 1. Typical SN75LVDS83B Load and Shift Sequences



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